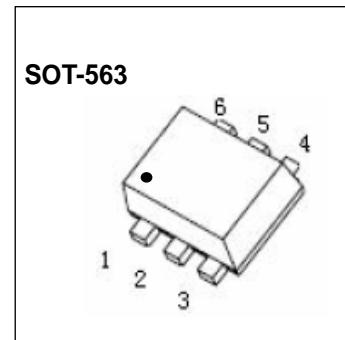




## **Plastic-Encapsulate MOSFETS**

## Dual P-Channel Power MOSFET

<b>V<sub>(BR)DSS</sub></b>	<b>R<sub>DS(on)MAX</sub></b>	<b>I<sub>D</sub></b>
-20V	750mΩ@-4.5V	
	11500mΩ@-2.5V	-0.66A
	2600mΩ(TYP)@-1.8V	



## **GENERAL DESCRIPTION**

This Dual P-Channel MOSFET has been designed using advanced Power Trench process to optimize the  $R_{DS(ON)}$ .

Including two P-ch CB3139K MOSFET (independently) in a package.

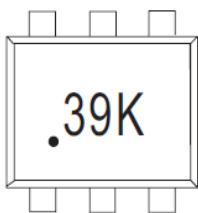
FEATURE

- High-Side Switching
  - Low On-Resistance
  - Low Threshold
  - Fast Switching Speed

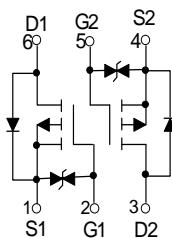
## APPLICATION

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
  - Battery Operated Systems
  - Power Supply Converter Circuits
  - Load/Power Switching Cell Phones, Pagers

## **MARKING**



## Equivalent Circuit



#### **Maximum ratings ( $T_a=25^\circ\text{C}$ unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source voltage	$V_{DSS}$	-20	V
Typical Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Drain Current-Continuous	$I_{D(DC)}$	-0.66	A
Drain Current -Pulsed(note1)	$I_{DM(\text{pulse})}$	-2.64	
Power Dissipation (note 2)	$P_D$	150	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	833	°C/W
Storage Temperature	$T_j$	150	°C
Junction Temperature	$T_{stg}$	-55 ~+150	

## MOSFET ELECTRICAL CHARACTERISTICS

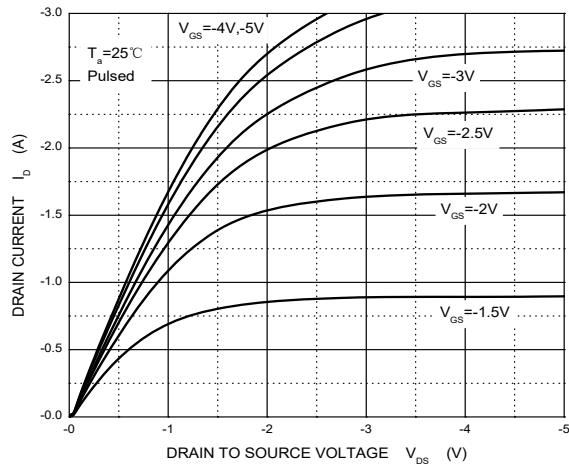
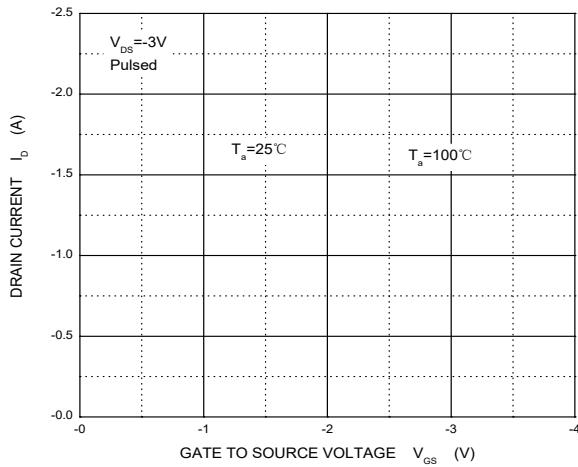
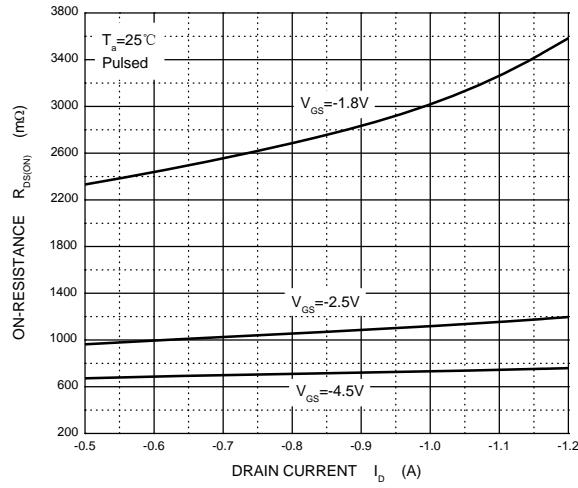
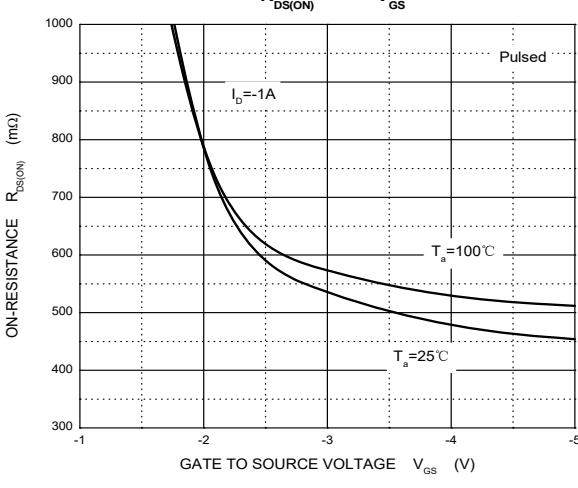
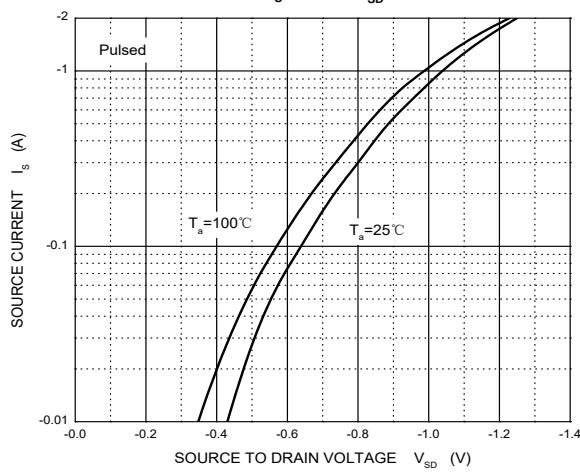
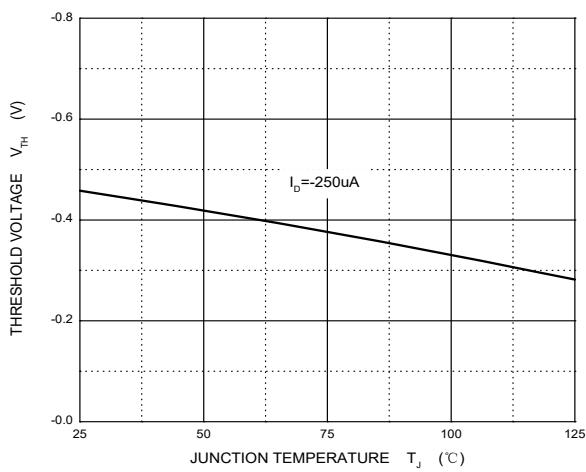
T<sub>a</sub>=25 °C unless otherwise specified

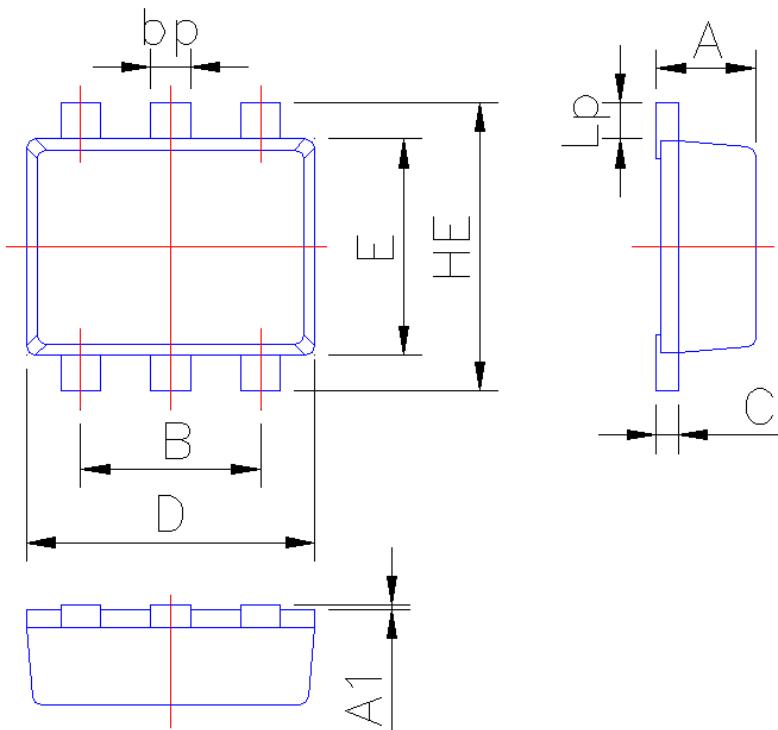
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>On/Off States</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Gate-Threshold Voltage(note 3)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.35		-1.1	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V			±20	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μA
Drain-Source On-State Resistance(note 3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1A			750	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -800mA			1150	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -500mA		2600		
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -540mA	0.8			S
<b>Dynamic Characteristics(note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, f = 1MHz			170	pF
Output Capacitance	C <sub>oss</sub>				25	
Reverse Transfer Capacitance	C <sub>rss</sub>				15	
<b>Switching Times (note 4)</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10V, I <sub>D</sub> = -200mA, V <sub>GS</sub> = -4.5V, R <sub>G</sub> = 10Ω			9	ns
Rise Time	t <sub>r</sub>				5.8	
Turn-Off Delay Time	t <sub>d(off)</sub>				32.7	
Fall Time	t <sub>f</sub>				20.3	
<b>Drain-Source Diode Characteristics</b>						
Drain-Source Diode Forward Voltage (note 3)	V <sub>SD</sub>	I <sub>S</sub> = -0.5A, V <sub>GS</sub> = 0V			-1.2	V

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. This test is performed with no heat sink at T<sub>a</sub>=25°C.
3. Pulse Test : Pulse Width≤300μs, Duty Cycle≤0.5%.
4. These parameters have no way to verify.

### Typical Characteristics

**Output Characteristics**

**Transfer Characteristics**

 **$R_{DS(ON)}$  —  $I_D$** 

 **$R_{DS(ON)}$  —  $V_{GS}$** 

 **$I_s$  —  $V_{SD}$** 

**Threshold Voltage**


**SOT-563-Package Outline Dimensions**


Symbol	Dimension in Millimeters	
	Min	Max
A	0.50	0.60
A1	0	0.05
B	0.95	1.05
bp	0.13	0.30
C	0.09	0.150
D	1.50	1.70
E	1.15	1.35
HE	1.40	1.80
Lp	0.13	0.30